Camalot 1818 Dispensing System

DESCRIPTION:

- SMT mount assembly and semiconductor packaging applications
  - Solder pastes, solder masks
  - Conductive adhesives
  - Gasketing, dam & fill
  - Glob-top encapsulation and flip chip underfill
- Dispense area: 457 mm x 457 mm max
- Resolution (XY axis): 0.0127 mm
- Max X / Y axis speed 254 mm/sec / 254 mm/sec
- Dispensing Methods
  - Rotary Auger, Multi-Piston Pump, and/or Time/Pressure
- Dispensing Rate
  - 16,000 dots/hour @ 0.020” centers
  - 13,000 dots/hour @ 0.125” centers

LOCATION: PROCESS DESIGN AND ANALYSIS LABORATORY, ROOM B7

CONTACT US

IEEC

BINGHAMTON UNIVERSITY

CONTACTS

For more information or to arrange for the use of this equipment, contact any of the IEEC staff members listed below:

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